

TECHNICAL DATA SHEET

KEPSTAN® 6001

POLYETHERKETONEKETONE PELLET OR FLAKE

KEPSTAN® is a high-performance thermoplastic material, based on PolyEtherKetoneKetone (PEKK) highly stable chemical backbone. KEPSTAN® is a unique member of the PAEK family, with distinctive structural features allowing for unrivalled possibilities in the control of crystallinity. These features include a high Ketone content and a co-polymer structure, incorporating Terephthalic and Isophthalic moieties.

The 6000 Series corresponds to the pseudo-amorphous products of the KEPSTAN® family, offering the lowest melting point and the slowest crystallization behavior, while keeping Tg close to 160°C. These properties allow for lower processing temperatures (as low as 320-330°C), and lead to amorphous or semi crystalline structures, depending on processing technologies and cooling conditions. The properties reported in the data sheet correspond to the amorphous state of the PEKK polymer.

KEPSTAN® 6001 is a very low flow grade of pure unfilled PEKK resin designed to meet the requirements of processing technologies requiring high viscosity, including among others extrusion, calendering, thermoforming, but also injection molding and powder coating.

TYPE

PEKK

MAIN APPLICATIONS

- Compounding

DELIVERY FORM

- Flakes
- Pellets

TRANSFORMATION PROCESSES

- Blow molding
- Calendering
- Injection Molding
- Thermoforming
- Transfer Molding

RHEOLOGICAL PROPERTIES

PROPERTIES	VALUE	UNIT	TEST STANDARD
Melt volume flow rate (MVR), 380°C / 5 kg (716°F / 11 lb)	15	cm³/10min	ISO 1133

MECHANICAL PROPERTIES

PROPERTIES	VALUE	UNIT	TEST STANDARD
Tensile modulus, 23°C (73°F), 1 mm/min(A12)	3100	MPa	ISO 527-1/-2
Yield stress, 23°C (73°F), 25 mm/min(A12)	89	MPa	ISO 527-1/-2
Yield strain, 23°C (73°F), 25 mm/min(A12)	5.6	%	ISO 527-1/-2
Nominal strain at break, 23°C (73°F), 25 mm/min(A12)	>70	%	ISO 527-1/-2
Charpy unnotched impact strength, 23°C (73°F)	No Break		ISO 179 1eU
Charpy unnotched impact strength, -30°C (-22°F)	No Break		ISO 179 1eU
Charpy notched impact strength, 23°C (73°F)	5.1	kJ/m2	ISO 179 1eA

KEPSTAN® 6001

THERMAL PROPERTIES

PROPERTIES	VALUE	UNIT	TEST STANDARD
Glass transition temperature, 23°C (73°F)(DSC)	158	°C	
Specific heat temperature, 23°C (73°F)(DSC)	1	J/g/K	
Heat deflection temperature, 1.8 MPa	139	°C	ISO 75-1/-2
Coefficient of linear thermal expansion, from -100°C (-148°F) to Tg(DMA, Tension)	26.5	10E-6 / °K	
Oxygen index(3.2mm)	43	%	ISO 4589-1/-2

ELECTRICAL PROPERTIES

PROPERTIES	VALUE	UNIT	TEST STANDARD
Dielectric strength(100µm Thickness)	84	kV/mm	IEC 60243-1
Relative permittivity, 23°C (73,4°F)(1MHz)	3		IEC 62631-2-1
Surface resistivity, 23°C (73,4°F)	100000000000000000	ohm.cm	ASTM D257
Volumic (transversal) resistivity, 23°C (73,4°F)	100000000000000000	ohm/sq	ASTM D257

OTHER PROPERTIES

PROPERTIES	VALUE	UNIT	TEST STANDARD
Moisture absorption, At equilibrium at 23°C (73°F) / 50%HR(2mm)	0.44	%	ISO 62
Moisture absorption, After 24h at 23°C (73°F)/50%RH(2mm)	0.07	%	ISO 62
Water absorption, 23°C (73°F), immersion, equilibrium(2mm)	1.07	%	ISO 62
Water absorption, 23°C (73°F)(After 24h, immersion, 2mm)	0.2	%	ISO 62
Apparent density, 23°C (73°F)	1.27	g/cm³	ISO 1183-1

PACKAGING

Available packaging:

- 20 kg / 44 lb boxes

SHELF LIFE

Indefinite when stored properly (sealed bags, appropriate UV protection and temperature)

PROCESSING CONDITIONS:

- Typical melt temperature (Min / Recommended / Max) - Injection Molding:Rear 300°C / Center 315°C / Front 320°C / Nozzle 330°C (570°F / 600°F / 610°F / 625°F)
- Typical mold temperature - Injection molding:80-120°C (175-250°F), below Tg in any case
- Drying time and temperature:120°C (250°F) / 6-8 hours

SPECIAL CHARACTERISTICS

- Halogen Free Flame Retardant (HFFR)

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